

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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| Title of Invention | MASK AND SUBSTRATE ALIGNMENT FOR SOLDER BUMP PROCESS |
| Application Number: | |

Confirmation Number:

First Named Applicant: Duane Allen

Attorney Docket Number: BUR920030027US1

Search string: (6327034 or 6274198 or 6030889 or 5324012 or 5296916 or 4915057 or 4755053 or 4746548 or 4544311 or 3647533 or 20010030747).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

| init | Cite.No. | Patent No. | Date | Patentee | Kind | Class | Subclass |
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| /AS/ | 1 | 6327034 | 2001-12-04 | Hoover et al | | | |
| /AS/ | 2 | 6274198 | 2001-08-14 | Dautartas | | | |
| /AS/ | 3 | 6030889 | 2000-02-29 | Aulicino et al | | | |
| /AS/ | 4 | 5324012 | 1994-06-28 | Aoyama et al | | | |
| /AS/ | 5 | 5296916 | 1994-03-22 | Kelly et al | | | |
| /AS/ | 6 | 4915057 | 1990-04-10 | Boudreau et al | | | |
| /AS/ | 7 | 4755053 | 1988-07-05 | Levinson et al | | | |
| /AS/ | 8 | 4746548 | 1988-05-24 | Boudreau et al | | | |
| /AS/ | 9 | 4544311 | 1985-10-01 | Husain | | | |
| /AS/ | 10 | 3647533 | 1972-03-07 | Hicks | | | |

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

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| /AS/ | 1 | 20010030747 | 2001-10-18 | Hoover et al | | | |

Signature

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|--------------------------------|------------|
| Examiner Name | Date |
| /Andre Stevenson/ (03/26/2008) | 03/26/2008 |

